



10-23-2002

ney Docket No. 16869P-052200US

Form PTO-1595 (Rev. 03-01) OMB No. 0651-0027 (exp. 5/31/2002)



...102258227

U.S. Department of Commerce U.S. Patent and Trademark Office

Tab settings

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof

1. Name of conveying party(ies): Motoko Kimura 10-15-02

Additional name(s) of conveying parties attached? [X] Yes [] No.

3. Nature of conveyance: [X] Assignment [] Merger [] Security Agreement [] Change of Name [] Other:

Execution Date: May 29, 2002

2. Name and address of receiving party(ies) Hitachi, Ltd. 6, Kanda Surugadai 4-chome Chiyoda-ku Tokyo, Japan

Additional names and addresses attached? [] Yes [X] No

4. Application number(s) or patent number(s).

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No(s): 10/192,478

B. Patent No(s):

Additional numbers attached? [] Yes [X] No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Robert C. Colwell TOWNSEND AND TOWNSEND AND CREW LLP Two Embarcadero Center, 8th Floor San Francisco, California 94111-3834 (415) 576-0200

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41): \$40.00

[] Enclosed [X] Authorized to be charged to deposit account

8. Deposit account number: 20-1430

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature. To the best of my knowledge and belief, the foregoing is true and correct and any attached copy is a true of copy of the original document.

Robert C. Colwell Name of Person Signing Atty. Reg. No. 27,431

Signature

October 8, 2002 Date

Total number of pages including cover sheet, attachments and document 3

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks, Box Assignments Washington, D.C. 20231

10/22/2002 TDIAZ1 00000171 201430 10192478 01 FC:8021 40.00 CH

1. Additional name(s) of conveying party(ies):
(Continued from Page 1)

Takeshi Miitsu
Takeshi Takahashi
Kaoru Katayama
Shiro Yamashita

2. Additional name(s) and address(es) of receiving party(ies):
(Continued from Page 1)

3. Additional application number(s) or patent number(s):
(Continued from Page 1)

A. Patent Application No.(s)

B. Patent No.(s)

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

METHOD FOR REMOVING SOLDER BUMPS FROM LSI

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Motoko Kimura</u>	<u>May 29, 2002</u>
2) <u>Takeshi Mitsu</u>	<u>May 31, 2002</u>
3) <u>Takeshi Tokatashi</u>	<u>May 31, 2002</u>
4) <u>Kaoru Katayama</u>	<u>May 31, 2002</u>
5) <u>Shiro Yamashita</u>	<u>June 4, 2002</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____